

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHEE KEONG ONG	03/04/2021
RECEIVING PARTY DATA	
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State/Country:	SINGAPORE
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17310284
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NAME OF SUBMITTER:	PAUL T. BOWEN
SIGNATURE:	/Paul T. Bowen/
DATE SIGNED:	12/13/2022
Total Attachments: 3	
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**CONFIRMATION OF ASSIGNMENT
Inventor(s) to ResMed Asia Pte. Ltd.**

WHEREAS, I/we, *Chuan Foong LEE, Min Li TEE, Marvin Sugi HARTONO, Angelene Marie OZOLINS, Chee Keong ONG*, an inventor, joint inventor, inventors or joint inventors (collectively hereinafter "Inventor") have made certain new and useful inventions relating to **SEAL-FORMING STRUCTURE, POSITIONING AND STABILIZING STRUCTURE AND DIFFUSER VENT FOR PATIENT INTERFACE**, (hereinafter "Inventive-Subject matter") which is described in and for which application has been made as follows:

- Patent Application filed on 8 April 2019 in United States of America and designated as Application No. 62/830,745.
- International (PCT) Patent Application filed on 7 April 2020 and designated as Application No. PCT/IB2020/053311

WHEREAS, **ResMed Asia Pte. Ltd.**, (hereinafter "Assignee"), a company incorporated in Singapore, whose postal address is 8 Loyang Crescent, #05-01 Singapore 50916, Singapore is desirous of acquiring the entire right, title and interest in and to said Inventive Subject-Matter, including without limitation said application(s), for every jurisdiction, including without limitation the United States of America and all other countries, and any benefits of or to be obtained therefrom:

NOW THEREFORE, in consideration of the sum of one dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, and on the Effective Date herein, Inventor has sold, assigned, and set over and/or to any extent not previously, by these presents does hereby sell, assign and set over unto Assignee and Assignee's legal representatives, successors and assigns, Inventor's entire right, title and interest in and to said Inventive Subject-Matter for every jurisdiction, including without limitation the United States of America and all other countries, said application(s) and any benefits of or to be obtained therefrom, including without limitation any continuation, including continuation-in-part, or divisional application, renewal or substitute thereof, international, foreign and regional applications corresponding or claiming priority thereto pursuant to any law or treaty, including the right to claim such priority or benefit, and the Letters Patent, both foreign and domestic, that may or shall issue thereon, or any reissue or re-examination thereof, and Inventor does hereby authorize and request the U.S. Commissioner of Patents and any other country's Commissioner

of Patents to issue said Letters Patent to the above-mentioned Assignee, consistent with the terms of this Assignment.

UPON SAID CONSIDERATION, Inventor hereby covenants and agrees with Assignee that Inventor has not and will not execute any writing or do any act whatsoever conflicting with these presents, and that Inventor will, at any time upon request, without further or additional consideration, but at the expense of Assignee, execute such additional assignments and other writings and do such additional acts as Assignee may deem necessary or desirable to perfect Assignee's or Assignee's assign's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, continuation, including continuation-in-part, or divisional application, renewal, substitute, reissued, re-examined or extended Letters Patent of the United States, or of any and all other countries, on said Inventive Subject-Matter, and in enforcing any rights or chose in action accruing as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of all parties.

And I/we do hereby authorize attorneys for Assignee to insert on this confirmation of assignment any additional filing date and application number and/or patent number of the aforementioned application(s) when known.

This Confirmation of Assignment may be executed in any number of counterparts and the executed counterparts together constitute an original.

EFFECTIVE DATE: 8 APRIL 2019

IN WITNESS WHEREOF, we have hereunto set our hands on the date indicated below.

Chuan Foong LEE

Date Signed

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Ltd., 8 Loyang Crescent, #05-01
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Min Li TEE

Date Signed

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Marvin Sugi HARTONO

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Angelene Marie OZOLINS

Date Signed

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DocuSigned by:

/ Chee Keong Ong /

March 4, 2021 | 12:15:00 AM EST

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Chee Keong ONG

Date Signed

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